TE Internal #: 1-1761465-1

Board-to-Board, 36 Position, 1 mm [.039 in] Centerline, Right Angle,

Black, 9.4 mm [.37 in] Height, PCI & PCI Express Connectors

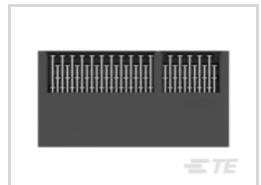
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Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors











Connector System: Board-to-Board

Number of Positions: 36

Centerline (Pitch): 1 mm [.039 in]

Termination Post & Tail Length: 3.1 mm [.122 in]

Contact Mating Area Plating Material Thickness: [30 µin]

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Sealable	No

Configuration Features

Number of PCB Mount Retention Features	2
Number of Positions	36
PCB Mount Orientation	Right Angle
Ejector	Without

Electrical Characteristics

Operating Voltage	50 VAC	

Body Features

Product Weight	21.302 g
Primary Product Color	Black

Contact Features

Contact Current Rating (Max)	1.1 A
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Contact Underplating Material	Nickel
Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin
	30 μin
Termination Features	
Termination Method to PCB	Through Hole - Solder
Termination Post & Tail Length	3.1 mm[.122 in]
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Housing Material	High Temperature Nylon
Centerline (Pitch)	1 mm[.039 in]
Dimensions	
PCB Thickness (Accepted)	1.57 mm[.062 in]
Connector Height	9.4 mm[.37 in]
Connector Width	19.6 mm[.772 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
Bus Type	PCI Express
Packaging Features	
Packaging Method	Box & Tray, Tray
Packaging Quantity	100

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant



China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Customers Also Bought























Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-1761465-1_C.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-1761465-1_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-1761465-1_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

4-1773442-7 Card Edge Connector for PCI Express Applications

English

Product Specifications

Application Specification

English